

COMPEQ

One-Stop PCB Service Provider

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COMPEQ continues to provide "One-Stop Service"

HDI PCB

Smart Phone
Tablet
Ultrabook
Wearable
Consumer



Flexible PCB

Battery module
LCD module
Camera module
Wearable
Accessory



SMT Assembly

Battery module
Automotive
Medical
Accessory

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One-Stop PCB Service Provider



Multilayer PCB

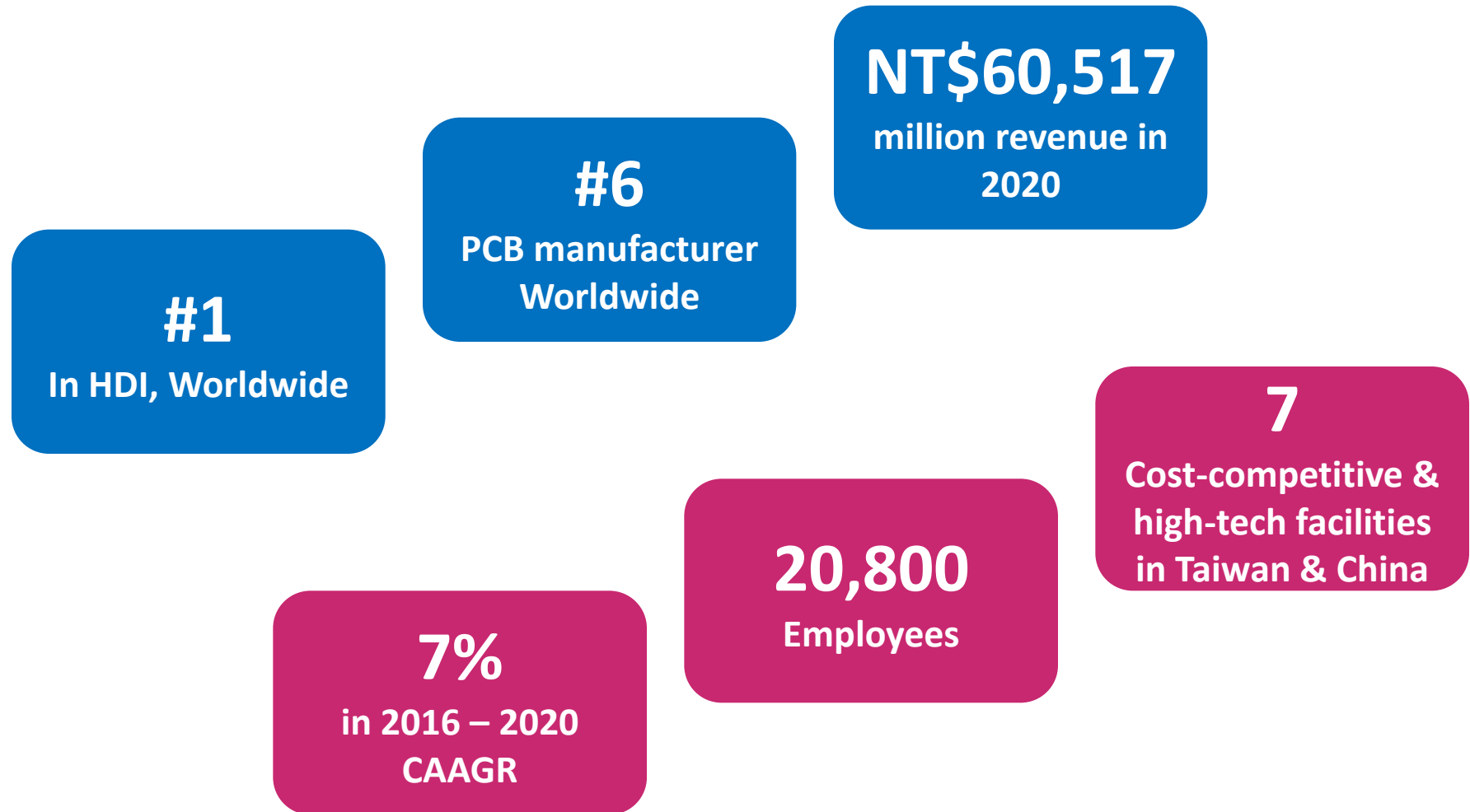
Satellite Communication
4/5G Base Station
Cloud Data computing
High Performance Networking



Rigid-Flex PCB

Battery module
LCD module
Camera module
Wearable

COMPEQ - Worldwide Leading High-tech PCB Vendor



Global Operations

● Facilities
 ■ Regional Office



Chongqing II
 Y2021
 600 employees
 92K M²



Chongqing I
 Y2014
 2,200 employees
 56K M²



Suzhou
 Y2004
 1,000 employees
 42K M²



Huizhou SMT
 Y2012
 1,700 employees
 27K M²



Huizhou FPC
 Y2004
 5,400 employees
 150K M²



Huizhou
 Y1996
 5,200 employees
 151K M²



Dayuan
 Y1998
 1,200 employees
 42K M²



Luzhu
 Y1973
 3,500 employees
 90K M²

COMPEQ Competitive Advantages

Quality

Compliant worldwide recognized quality standard and certifications.
Quality management system prioritized to fulfill customer specifications.

Technology

Leading 25/25 μ m line and spacing substrate-like Anylayer with mSAP,
Wide range high end hybrid multilayers, unique flex and rigid flex boards.

CSR

Long term commitment to community, employee, suppliers, customers and investors.
Focus on labor rights, business ethic, energy saving, and environment protection.

Service

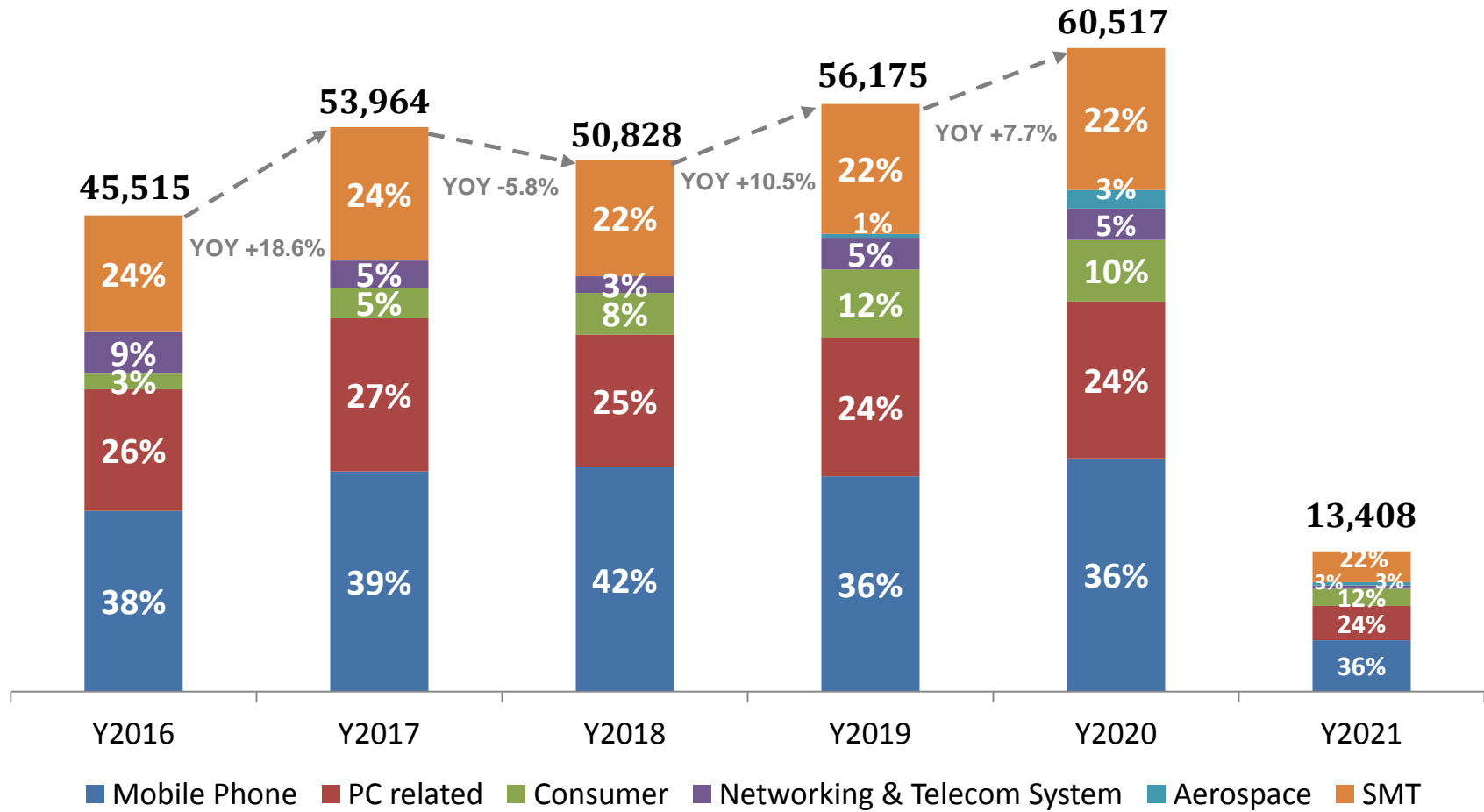
One-Stop Service, from design-for-manufacturing solution to field application support, worldwide service network to full product line include HDI, RPCB, RFPC, FPC to SMT.

Long term Partnership
















Steady growth under the sustainable business philosophy.

Operation Revenue – By Application

Units: MNTD













PCB Market Player/Position

| Rank | Country | Supplier | 2020 Revenue(MUSD) |
|------|---|--------------------|--------------------|
| 1 | TWN  | Zhen Ding | 4,442 |
| 2 | TWN  | Unimicron | 3,117 |
| 3 | JPN  | Nippon Mektron | 2,594 |
| 4 | CHN  | Dongshan Precision | 2,523 |
| 5 | USA  | TTM | 2,105 |
| 6 | TWN  | Compeq | 2,048 |
| 7 | TWN  | Tripod | 1,891 |
| 8 | CHN  | Shennan | 1,664 |
| 9 | TWN  | PSA | 1,557 |
| 10 | KOR  | SEMCO | 1,504 |
| 11 | JPN  | Ibiden | 1,444 |
| 12 | KOR  | Young Poong | 1,408 |
| 13 | CHN  | Kingboard | 1,356 |
| 14 | TWN  | Nan Ya | 1,312 |
| 15 | AUT  | AT&S | 1,290 |

Source: Prismark, 2021

PCB Market Player/Position - HDI Technology

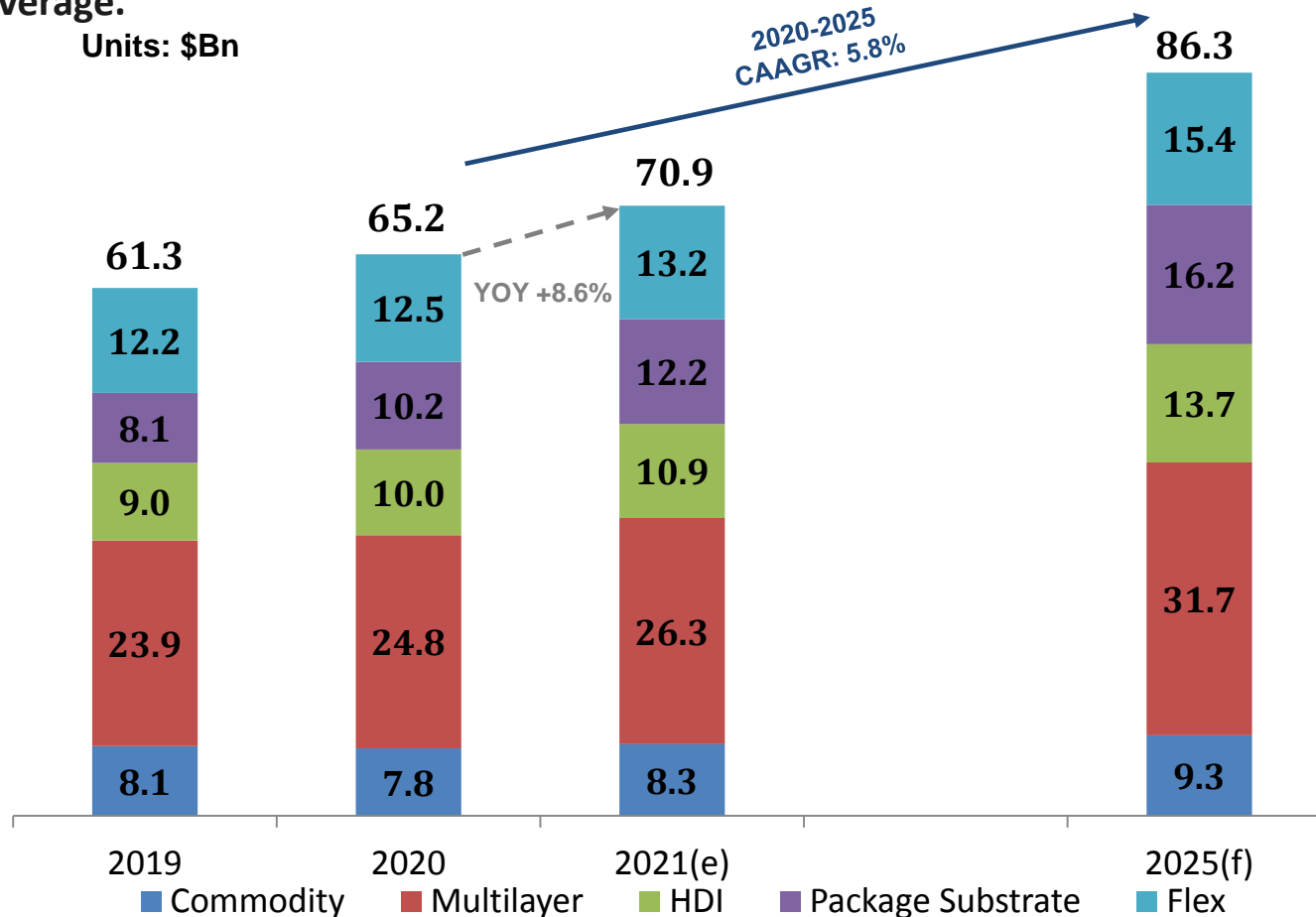
| Rank | Country | Supplier | 2019 Revenue(MUSD) |
|------|---|-------------|--------------------|
| 1 | TWN  | Compeq | 776 |
| 2 | AUT  | AT&S | 736 |
| 3 | USA  | TTM | 716 |
| 4 | TWN  | Unimicron | 706 |
| 5 | TWN  | Tripod | 508 |
| 6 | JPN  | Meiko | 461 |
| 7 | TWN  | Zhen Ding | 428 |
| 8 | KOR  | Young Poong | 226 |
| 9 | CHN  | Founder | 222 |
| 10 | JPN  | CMK | 220 |

Source: Prismark, 2020

PCB Market Trend

Prismark expects the PCB industry to grow by 8.6% over 2020. All segments are expected to improve as the electronics industry as a whole recovers in 2021, package substrates will continue to be the main driver.

Over the next few years, the 5G, Automotive, Wearable segment will continue to outpace the overall market, Prismark forecast 5.8% growth (CAAGR 2020-2025) in the near future, package substrate and HDI growth above average.



Source: Prismark, 2021



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Thank You For Your Attention